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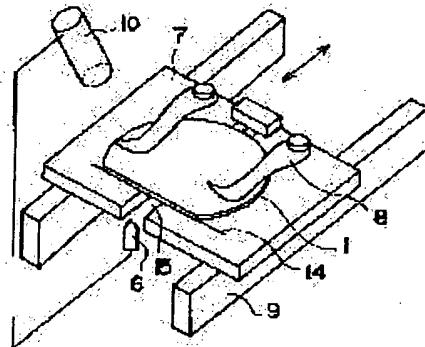
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(54) WAFER SCRIBER

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a device capable of easily performing cleavage when the cross section of a wafer is observed in order to confirm the process result in the production of a semiconductor by providing a cutter capable of accurately scribing the rear surface of the wafer.

SOLUTION: A sample wafer 1 is fixed with a leaf spring 8 on the stage 7 movable on a rail 9 back and forth. A cutter 6 composed of a diamond needle passes through the groove 15 provided to the stage 7 to scribe the rear surface of the wafer 1. An optical system 10 such as a magnifying glass is provided above the stage 7 and the optical system 10 and the cutter 6 are connected so as to cooperate with each other or so that only the cutter 6 is independently moved. Collimation such as a cross is attached to the visual field of the optical system 10 and, if the cutter 6 is slid so as to be matched with the position to be cut of the surface of the wafer 1, the rear surface of the wafer is scribed at a desired position. If proper tension is applied to the wafer 1, the wafer is cleaved along a scribing line without damaging the sample wafer to perform necessary observation.



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